

Amendments to the Claims:

Listing of the claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Canceled)

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2. (Currently Amended) A slider scale package assembly comprising:
a slider/MR head having opposing front and back sides, the front side defining an air bearing surface;
at least one interconnect pad disposed at the back of the slider/MR head; and
a flex circuit attached to a back the back of the slider/MR head in contact with the
at least one interconnect pad which turns the slider/MR head into the slider scale package
assembly with at least one interconnect pad disposed at the back of the slider/MR head.

3. (Currently Amended) The slider scale package assembly of claim 2, wherein the slider/MR head further includes a front end and at least one bond pad disposed thereon, and the
flex circuit further includes a conductive material that extends between the at least one
interconnect pad and the at least one bond pad, the at least one interconnect pad and the at least
one bond pad are is electrically connected to the conductive material of the flex circuit, the
slider/MR head includes at least one bond pad, the conductive material of the flex circuit is
electrically bonded to the at least one bond pad of the slider/MR head.

4. (Canceled)

5-7 (Canceled)

8. (Currently Amended) The slider scale package assembly of claim 3, wherein the flex circuit slider scale package assembly includes first, second, third, and fourth interconnect pads disposed on the back of the slider/MR head, and first, second, third, and fourth bond pads disposed on the front end of the slider/MR head, wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pads, and the slider/MR head includes first, second, third, and fourth bond pads wherein the at least one bond pad is one of the first, second, third or fourth bond pads.

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9. (Currently Amended) The slider scale package assembly of claim 8, wherein the first and second bond pads are electrically coupled to a first pair of positive and negative polarities of the slider/MR head for reading data, respectively, and the third and fourth bond pads are electrically coupled to a second pair of positive and negative polarities of the slider/MR head for writing data, respectively.

10. (Currently Amended) The slider scale package assembly of claim 9, wherein the first, second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads ~~of a head interconnect circuit~~ match with polarities ~~from the head interconnect circuit of the interconnect pads~~.

11. (Original) The slider scale package assembly of claim 10, wherein the first and second interconnect pads are electrically connected to the first and second bond pads of the slider/MR head, respectively, and the third and fourth interconnect pads are electrically connected to the third and fourth bond pads of the slider/MR head, respectively.

12-14 (Canceled)

15. (Currently Amended) A head gimbal assembly (HGA) for supporting a slider/magnetic recording (MR) head in a disc drive, the slider/MR head including opposing front and back side, the front side defining an air bearing surface, comprising:

a suspension supporting the slider/MR head;

a head interconnect circuit being attached to and disposed along the suspension, the head interconnect circuit including a conductive material; and

a slider scale package for electrically coupling the slider/MR head to the head interconnect circuit, ~~wherein the slider scale package comprises comprising the slider/MR head, a flex circuit attached to a to the back of the slider/MR head, and at least one interconnect pad disposed on the back of the slider/MR head and providing electrical contact with which turns the slider/MR head into the slider scale package with at least one interconnect pad disposed at the back of the slider/MR head, the at least one interconnect pad being electrically bonded to the conductive material of the head interconnect circuit.~~

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16. (Currently Amended) The HGA of claim 15, wherein the slider/MR head includes a front end and at least one bond disposed on the front end, and the flex circuit further includes a conductive material extending between the at least one bond pad and the at least one interconnect pad, and the slider/MR head includes at least one bond pad, the conductive material of the flex circuit is electrically connected to the at least one interconnect pad ~~at a first end~~ and to the at least one bond pad ~~of the slider/MR head at a second end~~.

17. (Currently Amended) The HGA of claim 16, wherein the flex circuit slider scale package assembly includes first, second, third, and fourth interconnect pads disposed on the back of the slider/MR head, and first, second, third, and fourth bond pads disposed on the front end of the slider/MR head, wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pads, and the slider/MR head includes first, second, third, and fourth bond pads wherein the at least one bond pad is one of the first, second, third or fourth bond pads.

18. (Previously presented) The HGA of claim 17, wherein the first and second bond pads are electrically coupled to a first pair of positive and negative polarities of the slider/MR head for reading data, respectively, and the third and fourth bond pads are electrically coupled to a second pair of positive and negative polarities of the slider/MR head for writing data, respectively, and the first, second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads match with polarities from the interconnect pads.

19-27 (Canceled)

28. (Original) A head gimbal assembly (HGA), of the type used for supporting a slider/magnetic recording (MR) head in an information storage device, the slider/MR head including opposing front and back side, the front side defining an air bearing surface, comprising:

- a) suspension means for supporting the slider/MR head;
- b) a head interconnect circuit secured to the suspension means, the head interconnect circuit including a conductive material; and
- c) a slider scale package, the slider scale package including the slider/MR head, a plurality of interconnect pads disposed at the back of the slider/MR head, and a flex circuit, the flex circuit attached to the back of the slider/MR head and electrically connected to the

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~~slider/MR head, secured to the back of the slider/MR head, and arranged and configured with a plurality of interconnect pads disposed at the back of the slider/MR head, wherein the plurality of interconnect pads are electrically connected to the conductive material of the head interconnect circuit.~~

29. (Original) The HGA of claim 28, wherein the flex circuit includes a first end, a second end, and a conductive material extending from the first end to the second end.

30. (Currently Amended) The HGA of claim 29, wherein the plurality of interconnect pads are located at the first end of the flex circuit, the slider/MR head includes a front end and a plurality of bond pads disposed at the front end, and the conductive material of the flex circuit is electrically connected to the interconnect pads at the first end and to the plurality of bond pads of the slider/MR head at the second end.

31. (Original) The HGA of claim 30, wherein the flex circuit includes first, second, third, and fourth interconnect pads.

32. (Original) The HGA of claim 30, wherein the slider/MR head includes first, second, third, and fourth bond pads.

33. (Currently Amended) The HGA of claim 30, wherein the flex circuit includes first, second, third, and fourth interconnect pads and the slider/MR head includes first, second, third, and fourth bond pads, and ~~wherein~~ the first, second, third and fourth interconnect pads of the flex circuit are electrically connected to the first, second, third and fourth bond pads of the slider/MR head, respectively, by the conductive material of the flex circuit.
